502728688 03/19/2014

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT2775294

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SATOSHI SHIMAMOTO	03/10/2014
TAKAAKI NODA	03/11/2014
TAKEO HANASHIMA	03/11/2014
YOSHIRO HIROSE	03/12/2014
HIROSHI ASHIHARA	03/10/2014
TSUKASA KAMAKURA	03/11/2014
SHINGO NOHARA	03/12/2014

RECEIVING PARTY DATA

Name:	Hitachi Kokusai Electric Inc.
Street Address:	14-1, Sotokanda 4-chome
Internal Address:	Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	1018980

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14219345

CORRESPONDENCE DATA

Fax Number: (301)762-4056

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via

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ATTORNEY DOCKET NUMBER: 1022.0041C

NAME OF SUBMITTER: PATRICK J. FINNAN

SIGNATURE: /Patrick J. Finnan/

502728688 PATENT REEL: 032474 FRAME: 0466

DATE SIGNED:	03/19/2014	
	This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 3		
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PATENT REEL: 032474 FRAME: 0467

COMBINED DECLARATION (37 CFR 1.63) AND ASSIGNMENT FOR UTILITY OR DESIGN APPLICATION

Title of Invention

METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, SUBSTRATE PROCESSING APPARATUS, SUBSTRATE PROCESSING SYSTEM AND NON-TRANSITORY COMPUTER-READABLE RECORDING MEDIUM

DECLARATION

As a below named inventor, I hereby declare that:

This declaration is directed to the above-identified application for United States Letters Patent and further identified by the Attorney Docket Number provided above in the header of this document.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose to the Office all information known to me to be material to patentability as defined in 37 CFR §1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

For good and valuable consideration, the undersigned inventor(s), hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Hitachi Kokusai Electric Inc.**, a corporation organized and existing under the laws of Japan, having its principal place of business at c/o Hitachi Kokusai Electric Inc., 14-1. Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the above-identified application for United States Letters Patent, and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements:

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

PATENT REEL: 032474 FRAME: 0468

grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.				
LEGAL NAME OF JOINT INVENTOR				
Inventor: Satoshi, SHIMAMOTO				
Having an address at: <u>c/o Hitachi Kokusai Electric Inc., 1, Yasuuchi 2 –chome, Yatsuo-machi,</u>				
Toyama-shi, Toyama 9392393, Japan				
Signature: Satoshi Shinanoto Date: March 10, 2014				
LEGAL NAME OF JOINT INVENTOR				
Inventor:Takaaki, NODA				
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Signature: Taknaki Moda Date: March 11, 2014				
LEGAL NAME OF JOINT INVENTOR				
Inventor: Takeo, HANASHIMA				
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Toyama-shi, Toyama 9392393, Japan				
Signature: Takeo Hanashima Date: March 11, 2014				
Note: An application data sheet (PTO/SB/14 or equivalent), naming the entire inventive entity, either accompanies this form or was filed previously and thus is currently of record in the file.				

PATENT REEL: 032474 FRAME: 0469

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Toyama-shi, Toyama 9392393, Japan				
Signature: Yoshiro Hirose	Date: Merch 12, 2014			
LEGAL NAME OF JOINT INVENTOR				
Inventor: Hiroshi, ASHIHARA				
Having an address at: <u>c/o Hitachi Kokusai Electric Inc.</u>	. 1, Yasuuchi 2 –chome, Yatsuo-machi,			
Toyama-shi, Toyama 9392393, Japan				
Signature: <u>Hiroshi Ashihara</u>	Date: March 10, 2014			
LEGAL NAME OF JOINT INVENTOR				
Inventor: Tsukasa, KAMAKURA				
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Toyama-shi, Toyama 9392393, Japan				
Signature: Tukasa Kamahwa	Date: <u>March</u> 11, 2014			
LEGAL NAME OF JOINT INVENTOR				
Inventor: Shingo, NOHARA				
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Toyama-shi, Toyama 9392393, Japan				
Signature: Singo Nolara	Date: Mord 12 2014			
Note: An application data sheet (PTO/SB/14 or equivalent), naming the entire inventive entity, either				
accompanies this form or was filed previously and thus is currently of record in the file.				

PATENT REEL: 032474 FRAME: 0470

RECORDED: 03/19/2014